Specification of Thermoelectric Module TES1-01715

Description

The 17 couples, 10 mm × 10 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

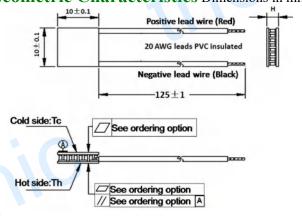
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N ₂	
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U _{max} (Voltage)	2.24	2.42	Voltage applied to the module at DT _{max}	
I _{max} (amps)	1.7	1.7	DC current through the modules at DT _{max}	
Q _{Cmax} (Watts)	2.41	2.64 Cooling capacity at cold side of the module under DT=0 °C		
AC resistance (ohms)	1.0	1.07	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness	Flatness/Paralle	Lead wire length(mm)		
	(mm)	lism (mm)	Standard/Optional length		
TF	$0.3.95 \pm 0.1$	0:0.03/0.03	$125 \pm 1/\text{Specify}$		
TF	$1: 3.95 \pm 0.03$	1:0.015/0.015	$125 \pm 1/\text{Specify}$		
Eg. TF01: Thickness 3.95 ± 0.1 (mm) and Flatness $0.015/0.015$ (mm)					

Manufacturing Options

A. Solder:

B. Sealant:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

3. T240: SbSn (Tmelt = 240° C)

3. EPS: Epoxy sealant

C. Ceramics:

D. Ceramics Surface Options:

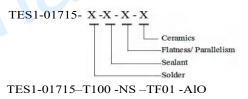
1. Alumina (Al₂O₃, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

Naming for the Module



T100: BiSn(Tmelt=138°C)

NS: No sealing

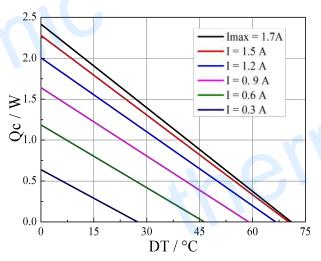
AlO: Alumina white 96%

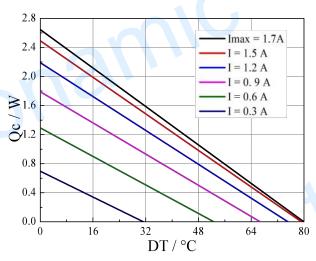
Specification (TF01: Thickness ± 0.1 (mm) and Flatness/Parallelism 0.025/0.025(mm)

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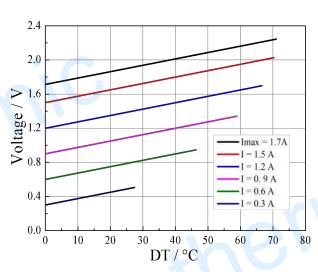


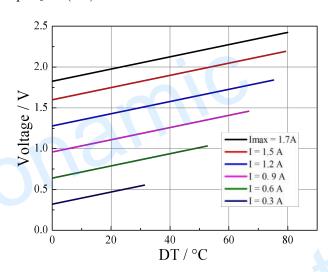
Performance Curves at Th=50 °C



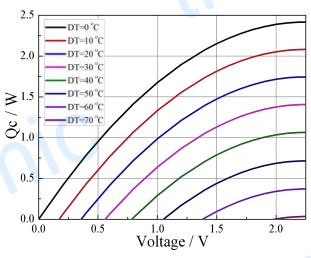


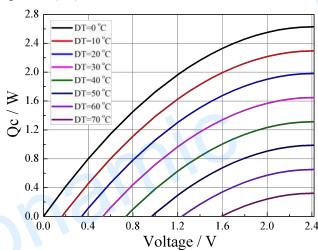
Standard Performance Graph Qc= f(DT)





Standard Performance Graph $V = f(\Delta T)$





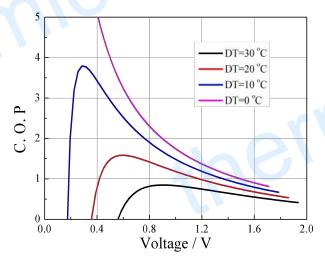
Standard Performance Graph Qc = f(V)

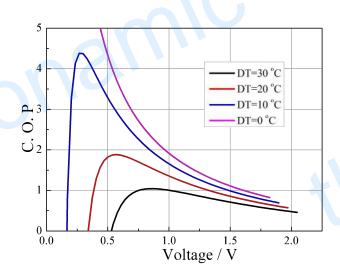
Specification of Thermoelectric Module

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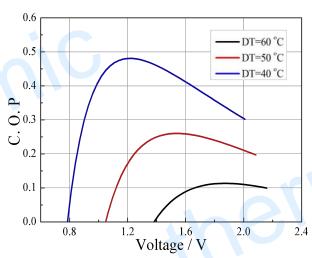
Performance Curves at Th=27 °C

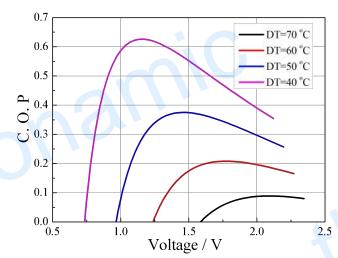
Performance Curves at Th=50 °C





Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Storage module below 100 °C
- Operation below I_{max} or V_{max}
- Work under DC